



## ABSTRACT

An assembly having a thermosetting layer pierced by a plurality of conductors is formed on a release sheet and subsequently sandwiched between an IC and a PWB or other supporting surface and subsequently cured. The release sheet is removed either before or  
5 during curing of the thermosetting material. Removal prior to curing may be accomplished via peeling. Removal during curing may be by destruction of the layer by the curing process.

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